

SOT1361-1

UFBGA24: plastic ultra thin fine-pitch ball grid array package;
24 balls

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	UFBGA24
Package type industry code	UFBGA24
Package style descriptive code	BGA (ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	7-11-2013

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	1.9	-	2	2.1	mm
E	package width	1.9	-	2	2.1	mm
A	seated height	[tbd]	-	[tbd]	0.65	mm
e	nominal pitch	-	-	0.4	-	mm
n ₂	actual quantity of termination	-	-	24	-	



2. Package outline

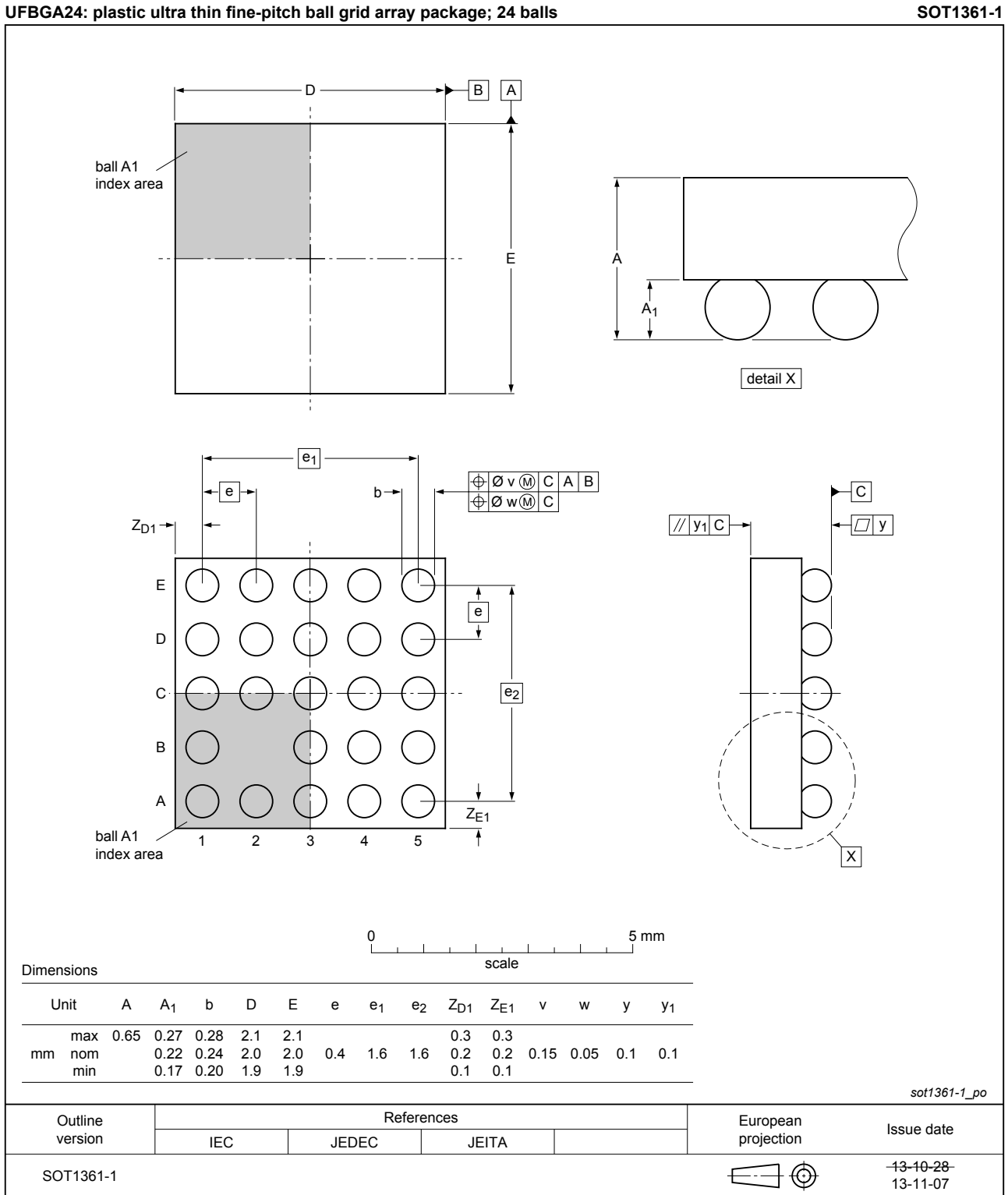


Fig. 1. Package outline UFBGA24 (SOT1361-1)

3. Legal information

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